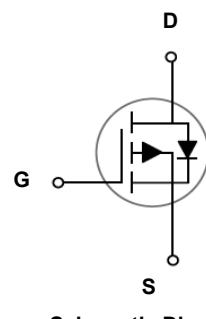
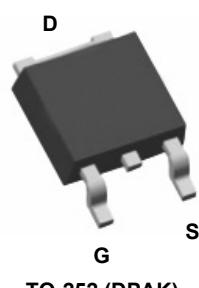


Main Product Characteristics

BV_{DSS}	-40V
$R_{DS(ON)}$	15mΩ (max.)
I_D	-40A



Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSFD4015 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{(BR)DSS}$	-40	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous, $T_C=25^\circ\text{C}$, $V_{GS}=10\text{V}^1$	I_D	-40	A
Drain Current-Continuous, $T_C=100^\circ\text{C}$, $V_{GS}=10\text{V}^1$		-27	
Drain Current-Pulsed ²	I_{DM}	-160	A
Pulsed Source Current (Body Diode) ²	I_{SM}	-160	A
Maximum Power Dissipation ($T_C=25^\circ\text{C}$) ³	P_D	80	W
Single Pulse Avalanche Energy, ($L=0.3\text{mH}$)	E_{AS}	245	mJ
Single Pulse Avalanche Current, ($L=0.3\text{mH}$)	I_{AS}	40	A
Junction-to-Ambient, ($t \leq 10\text{s}$) ⁴	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$
Maximum Junction-to-Case ⁵	$R_{\theta JC}$	1.56	$^\circ\text{C}/\text{W}$
Operating Junction Temperature Range	T_J	-55 To +150	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 To +150	$^\circ\text{C}$

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On / Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_D=-250\mu\text{A}$	-40	-	-	V
Drain-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=-40\text{V}, V_{\text{GS}}=0\text{V}$	-	-	-1	μA
		$V_{\text{DS}}=-40\text{V}, V_{\text{GS}}=0\text{V}$ $T_J=125^\circ\text{C}$	-	-	-50	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	±100	nA
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-10\text{V}, I_D=-20\text{A}$	-	11	15	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_D=-10\text{A}$	-	15	20	
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_D=-250\mu\text{A}$	-1	-1.6	-3	V
Dynamic and Switching Characteristics						
Total Gate Charge	Q_g	$V_{\text{DD}}=-20\text{V}, I_D=-20\text{A}$ $V_{\text{GS}}=-10\text{V}$	-	67	-	nC
Gate-Source Charge	Q_{gs}		-	11	-	
Gate-to-Drain Charge	Q_{gd}		-	12	-	
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=-30\text{V}, R_G=3\Omega,$ $R_L=1.5\Omega, V_{\text{GS}}=-10\text{V},$ $I_D=-20\text{A}$	-	8	-	nS
Rise Time	t_r		-	26.5	-	
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	105.2	-	
Fall Time	t_f		-	142.1	-	
Input Capacitance	C_{iss}	$V_{\text{DS}}=-20\text{V}, V_{\text{GS}}=0\text{V},$ $F=1\text{MHz}$	-	3680	-	pF
Output Capacitance	C_{oss}		-	264	-	
Reverse Transfer Capacitance	C_{rss}		-	294	-	
Gate Resistance	R_g	$F=1\text{MHz}$	-	4.3	-	Ω
Drain-Source Diode Characteristics and Maximum Ratings						
Maximum Body-Diode Continuous Current	I_s	MOSFET symbol showing the integral reverse p-n junction diode.	-	-40	-	A
Maximum Body-Diode Pulse Current	I_{SM}	$V_{\text{GS}}=0\text{V}, I_s=-20\text{A}$ $T_J=25^\circ\text{C}$	-	-160	-	A
Diode Forward Voltage	V_{SD}		-	-0.8	-1.2	V
Reverse Recovery Time	T_{rr}	$T_J=25^\circ\text{C}, I_F=-30\text{A},$ $di/dt=100\text{A}/\mu\text{s}$	-	15.5	-	nS
Reverse Recovery Charge	Q_{rr}		-	10.5	-	nC

Note:

- Calculated continuous current based on maximum allowable junction temperature.
- Repetitive rating; pulse width limited by max. junction temperature.
- The power dissipation P_D is based on max. junction temperature, using junction-to-case thermal resistance.
- The value of $R_{\theta,\text{JA}}$ is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

Typical Electrical and Thermal Characteristic Curves

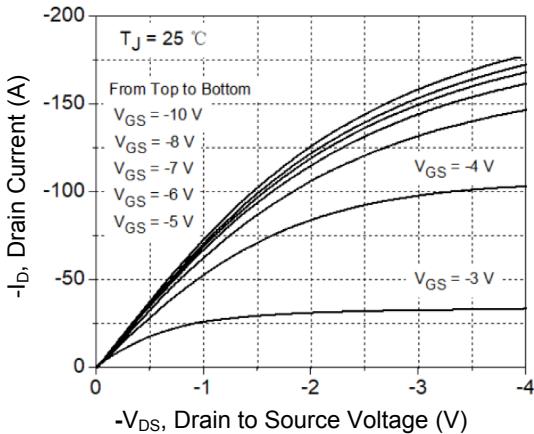


Figure 1. Typical Output Characteristics

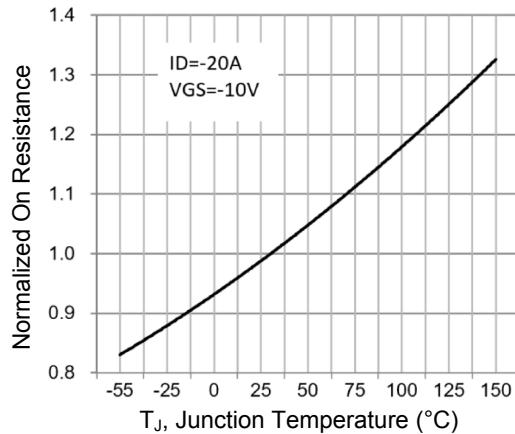


Figure 2. Normalized $R_{DS(on)}$ vs. T_J

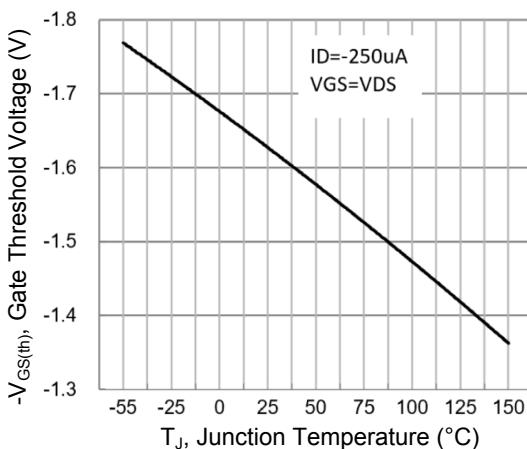


Figure 3. Gate Threshold Voltage vs. T_J

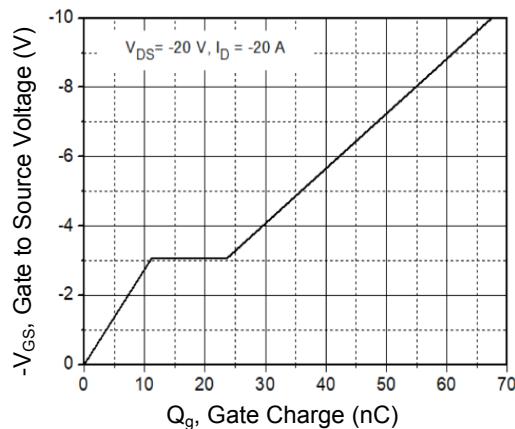


Figure 4. Gate Charge Characteristics

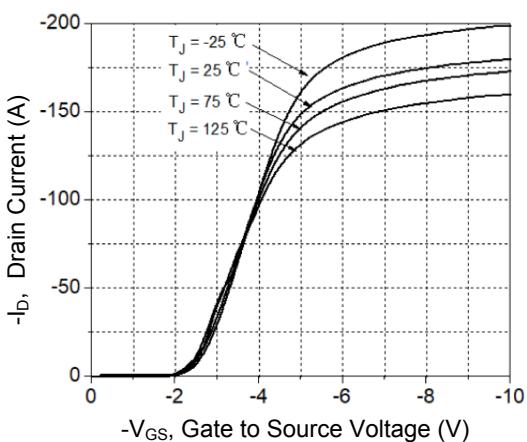


Figure 5. Transfer Characteristics

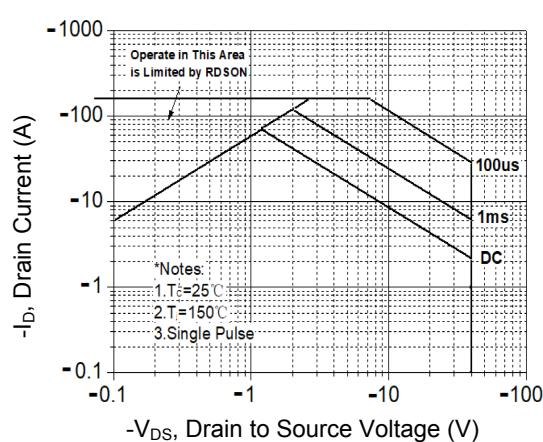
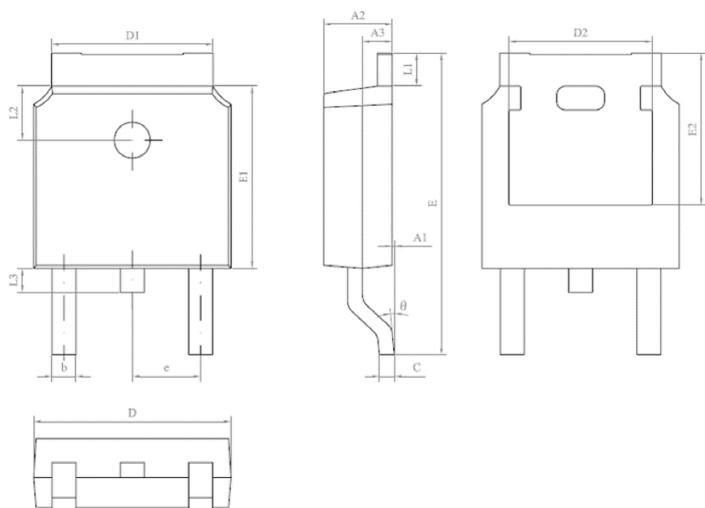


Figure 6. Safe Operation Area

Package Outline Dimensions TO-252 (DPAK)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A1	0.000	0.100	0.000	0.004
A2	2.200	2.400	0.087	0.094
A3	0.090	1.100	0.004	0.043
b	0.750	0.850	0.030	0.033
C	0.500	0.600	0.020	0.024
D	6.500	6.700	0.256	0.264
D1	5.300	5.500	0.209	0.217
D2	4.700	4.900	0.185	0.193
E	9.900	10.300	0.390	0.406
E1	6.000	6.200	0.236	0.244
E2	5.000	5.200	0.197	0.205
e	2.400	2.200	0.094	0.087
L1	0.900	1.250	0.035	0.049
L2	1.700	1.900	0.067	0.075
L3	0.600	1.000	0.024	0.039
θ	0°	8°	0°	8°